



## PATENT

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Salman Akram

**Serial No.:** 10/033,233

**Filed:** December 28, 2001

**For:** CHIP PACKAGE WITH GREASE  
HEAT SINK AND METHOD OF MAKING

**Confirmation No.:** 9685

**Examiner:** K. Nguyen

**Group Art Unit:** 2823

**Attorney Docket No.:** 2269-6890.1US  
(99-0439.01/US)

**Notice of Allowance Mailed:**

January 26, 2005

**NOTICE OF EXPRESS MAILING**

Express Mail Mailing Label Number: EL994848781US

Date of Deposit with USPS: April 26, 2005

Person making Deposit: Steven P. Wong

**TRANSMITTAL LETTER**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Applicant submits herewith Part B - Fee(s) Transmittal for the above-captioned application and a check in the amount of \$1715.00 in payment therefor plus five (5) copies of the patent when issued.

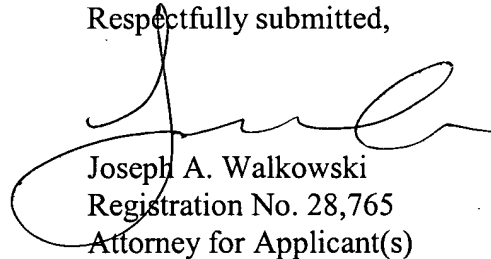
Also, enclosed herewith are the following documents:

1. Amendment Pursuant to 37 C.F.R. § 1.312(a);

2. Annotated sheets showing changes made (12 sheets);
3. Replacement formal drawings (4 sheets);
4. Comments on Statement of Reasons for Allowance (2 pages);
5. Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees; and
6. Power of Attorney (37 C.F.R. § 1.34 (a)), Revocation of Prior Power of Attorney (37 C.F.R. § 1.33 (d)) and Request to Change Correspondence Address (37 C.F.R. § 1.33 (d)) with Statement Pursuant to 37 C.F.R. § 3.73.

Applicant understands that no additional fees are required. However, if the Office determines that any comparison fees or other additional fees are required, the Commissioner is authorized to charge any such fees to TraskBritt Deposit Account No. 20-1469. A copy of this Transmittal Letter is enclosed for deposit account charging purposes.

Respectfully submitted,



Joseph A. Walkowski  
Registration No. 28,765  
Attorney for Applicant(s)  
TRASKBRITT  
P.O. Box 2550  
Salt Lake City, Utah 84110-2550  
Telephone: 801-532-1922

Date: April 26, 2005  
JAW/djp:slm

Enclosures: Part B - Fee(s) Transmittal  
Check No. 7731 in the amount of \$1715.00  
Copy of Transmittal Letter  
Amendment Pursuant to 37 C.F.R. § 1.312(a)  
Annotated sheets showing changes made (12 sheets)  
Replacement formal drawings (4 sheets)  
Comments on Statement of Reasons for Allowance (2 pages)  
Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages)  
Power of Attorney (37 C.F.R. § 1.34 (a)), Revocation of Prior Power of Attorney (37 C.F.R. § 1.33 (d)) and Request to Change Correspondence Address (37 C.F.R. § 1.33 (d)) with Statement Pursuant to 37 C.F.R. § 3.73 (2 pages)



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**COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE**

Mail Stop Issue Fee  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

The Examiner indicates:

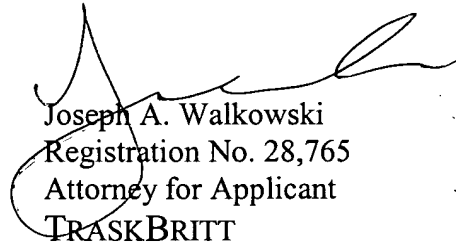
[(See Applicant's Amendment and Response submitted on May 17<sup>th</sup>, 2004, on page 8, lines 3-12)]

The prior art taken alone or in combination neither discloses nor makes obvious the instant process of claims as a whole. Specifically, the prior art of record, Mu (U.S. Patent 4,887,148) discloses a method of making an IC chip package having an IC chip with an active surface, the active surface having extending therefrom an electrical connector in electrical communication with IC chip, the IC chip being mounted upon a substrate, the method comprising (col. 3, line 4 to col. 4, line 15 and FIGS. 1-5): providing a container (FIG. 1: 22, 52) disposed upon the

substrate, the container in contact with the active surface of the IC chip (FIG. 1: 18); and injecting a grease (FIG. 1: 20) in contact with the active surface of the IC chip such that the grease is enclosed by the container and the substrate (col. 5, lines 10-33); and is in contact with the active surface and the electrical connector (FIG. 1: 44) but fails to teach or suggest the Applicant's steps of providing a second IC chip having an active surface and being disposed over the first side of the BOC substrate; providing a container disposed upon the BOC substrate, the container in contact with the active surface of the first IC chip; and inject a grease between the BOC substrate and the containers as recited in the independent claim 16, lines 6-10.]

Applicant concurs with the reasons as stated by the Examiner insofar as they comprise a summary, and are exemplary and not limiting. However, the scope of the claims must be determined from the literal language of each as a whole, as well as equivalents thereof.

Respectfully submitted,



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Date: April 26, 2005  
JAW/dlm:sm

Document in ProLaw